



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-01-30
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS61L45CT	H8DZ*Z15Q02Y	A	9945	2019-01-30
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 26th October 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.67	Die - Leadframe	354
Lead	13.96	Soft solder	7347

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	13.96	Soft solder	7347
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	13.96	Soft solder	955049

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	H8D2*Z15Q02Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	17.082	mg	supplier	die	Silicon (Si)	7440-21-3		16.067	mg	940581	8456
				supplier	metallization	Aluminium (Al)	7429-90-5		0.665	mg	38930	350
				supplier	metallization	Nickel (Ni)	7440-02-0		0.072	mg	4215	38
				supplier	metallization	Titanium (Ti)	7440-32-6		0.015	mg	878	8
				supplier	metallization	Tungsten (W)	7440-33-7		0.024	mg	1405	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.098	mg	5737	52
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.008	mg	468	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.023	mg	1346	12
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.110	mg	6440	58
Leadframe	M-004 Copper and its alloys	1253.534	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.375	mg	998278	658618
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
				supplier	metallization	Nickel (Ni)	7440-02-0		0.490	mg	391	258
				supplier	metallization	Phosphorus (P)	7723-14-0		0.040	mg	31	22
Soft solder	Solder	14.616	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	13.959	mg	955049	7347
				supplier	solder	Silver (Ag)	7440-22-4		0.365	mg	24973	192
				supplier	solder	Tin (Sn)	7440-31-5		0.292	mg	19978	154
Bonding wires	M-011 Other inorganic materials	9.413	mg	supplier	wire	Aluminium (Al)	7429-90-5		9.413	mg	1000000	4954
Encapsulation	M-011 Other inorganic materials	598.993	mg	supplier	mold compound	Silica, vitreous	60676-86-0		521.124	mg	870000	274276
				supplier	mold compound	Epoxy resin	25068-38-6		59.899	mg	100000	31526
				supplier	mold compound	Phenol resin	29690-82-2		14.975	mg	25000	7881
				supplier	mold compound	Carbon Black	1333-86-4		2.995	mg	5000	1576
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348